



Material Content Data Sheet



Sales Product Name				BTS410F2 E3062A		Issued		23. January 2018	
MA#				MA001118864					
Package				PG-TO263-5-2		Weight*		1498.68 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	6.117	0.41	0.41	4082	4082	
leadframe	inorganic material	phosphorus	7723-14-0	0.237	0.02		158		
	non noble metal	iron	7439-89-6	0.790	0.05		527		
	non noble metal	copper	7440-50-8	788.527	52.61	52.68	526149	526834	
	non noble metal	aluminium	7429-90-5	1.522	0.10	0.10	1016	1016	
wire	non noble metal	aluminium	7429-90-5	1.522	0.10	0.10	1016	1016	
encapsulation	organic material	carbon black	1333-86-4	6.319	0.42		4216		
	inorganic material	antimonytrioxide	1309-64-4	13.212	0.88		8816		
	plastics	brominated resin	-	14.935	1.00		9965		
	plastics	epoxy resin	-	109.140	7.28		72824		
	inorganic material	silicondioxide	60676-86-0	430.816	28.75	38.33	287463	383284	
leadfinish	non noble metal	tin	7440-31-5	10.339	0.69	0.69	6899	6899	
plating	inorganic material	phosphorus	7723-14-0	0.008	0.00		5		
	non noble metal	nickel	7440-02-0	3.422	0.23	0.23	2283	2288	
solder	non noble metal	tin	7440-31-5	0.104	0.01		70		
	noble metal	silver	7440-22-4	0.130	0.01		87		
	non noble metal	lead	7439-92-1	4.978	0.33	0.35	3321	3478	
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		22		
	non noble metal	iron	7439-89-6	0.108	0.01		72		
	non noble metal	copper	7440-50-8	107.943	7.20	7.21	72025	72119	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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